WHAT IS CLAIMED:

1. A method for electrically coupling together at least two electrically conductive layers of a printed circuit board, the method comprising the steps of:

forming at least one through-hole in the printed circuit board; and

inserting in the at-least-one through-hole an electrically conductive stake for electrically coupling foils disposed on the at least two electrically conductive layers together.

2. The method of claim 1 wherein the conductive stake has a polygonal shape, and the inserting step inserts the conductive stake such that at least one point of the polygonal shape makes contact with the foils.

3. The method of claim 1 wherein the conductive stake has conductive fins attached along a length of the conductive stake, and the inserting step inserts the conductive stake such that at least one conductive fin makes contact with the foils.

4. The method of claim 1 wherein the inserting step inserts the conductive stake such that the conductive stake is substantially disposed within the printed circuit board.

5. The method of claim 1 wherein the inserting step inserts the conductive stake such that a portion of the conductive stake extends beyond a surface of the printed circuit board.

6. A printed circuit board comprising:

at least three layers of material, such that two of the layers of material are electrically conductive and the third layer is an electrical insulator and wherein the insulating layer is disposed between the conductive layers; and

at least one conductive stake inserted into the printed circuit board for forming a via for electrically connecting foils from the two conductive layers together.

7. The printed circuit board of claim 6 wherein the conductive stake has a polygonal shape and is inserted such that at least one point of the polygonal shape makes

contact with the foils for forming the via.

8. The printed circuit board of claim 6 wherein the conductive stake has conductive fins attached along a length of the conductive stake, and is inserted such that at least one conductive fin makes contact with the foils for forming the via.

9. The printed circuit board of claim 6 wherein the conductive stake is substantially disposed within the printed circuit board.

10. The printed circuit board of claim 6 wherein a portion of the conductive stake extends beyond a surface of the printed circuit board.

11. A printed circuit board comprising:

at least four conductive layers of material; and

at least two conductive stakes inserted into a through hole of the printed circuit board for forming at least two different vias, one via electrically connecting together foils from two of the four conductive layers and the other via electrically connecting together foils from the remaining two of the four conductive layers.

12. The printed circuit board of claim 11 wherein at least one conductive stake has a polygonal shape, and is inserted such that at least one point of the polygonal shape makes contact with foils from two of the four conductive layers.

13. The printed circuit board of claim 11 wherein at least one conductive stake has conductive fins attached along a length of the conductive stake, and is inserted such that at least one conductive fin makes contact with foils from two of the four conductive layers.

14. The printed circuit board of claim 11 wherein at least one of the conductive stakes is substantially disposed within the printed circuit board.

15. The printed circuit board of claim 11 wherein a portion of at least one of the conductive stakes extends beyond a surface of the printed circuit board.